



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Sectionals *	A-D <i>* : Required Field</i>

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2015-06-29
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Rossana Bonaccorso	Representative Title	IPD MD CHAMPION
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

While STMicroelectronics has endeavored to provide information which is accurate and up to date, this document and its contents are provided on a strict 'as is' and 'as available' basis. STMicroelectronics disclaims all warranties, express or implied related to this document and its contents, including but not limited to implied warranties of completeness, truth, accuracy, merchantability, fitness for a particular purpose and non-infringement. ST shall have no responsibility and assumes no liability for any cost, loss or damage of any kind which could arise, directly or indirectly, from the use or inability to use this document and/or its contents.


Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard
------------------------------	-------------	----------------------------	-----------------

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	8HZK*TWU030K	A	ZA41	2015-06-29
Amount	UoM	Unit type	ST ECOPACK Grade	
250.00	mg	Each	ECOPACK® 2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
SOJ	4.5X2.16X3.68	1	J bend	
Comment	Package: SMC CLIP (SOD 15 NEW), MD valid for CP:SM15T30A, SMCJ26A-TR.			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	false
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	true
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
5 - Product(s) is obsolete, no information is available	false
6 - Product(s) is unknown, no information is available	false
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : REACH-17th December 2014				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	8HZK*TWU030K					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or Dies (choose)	Other inorganic materials	5.548	mg	supplier	die	Silicon (Si)	7440-21-3		4.918	mg	886421	19636
				supplier	metallization	Aluminium (Al)	7429-90-5		0.528	mg	95161	2108
				supplier	Passivation	Silicon Oxide	7631-86-9		0.045	mg	8126	180
				supplier	back side metallization	Aluminium (Al)	7429-90-5		0.019	mg	3431	76
				supplier	back side metallization	Gold (Au)	7440-57-5		0.007	mg	1264	28
Leadframe	Copper and its alloy	88.356	mg	supplier	back side metallization	Nickel (Ni)	7440-02-0		0.031	mg	5598	124
				supplier	alloy	Copper (Cu)	7440-50-8		88.313	mg	999512	352628
				supplier	alloy	Zinc (Zn)	7440-66-6		0.004	mg	45	16
				supplier	alloy	Iron (Fe)	7439-89-6		0.009	mg	102	36
				supplier	alloy	Phosphorus (P)	12185-10-3		0.030	mg	340	120
Die Attach	Other organic material	4.207	mg	JIG - R	soft solder	Lead (Pb)	7439-92-1	7a. Lead in high me	3.892	mg	925000	15540
				supplier	soft solder	Tin (Sn)	7440-31-5		0.210	mg	50000	840
				supplier	soft solder	Silver (Ag)	7440-22-4		0.105	mg	25000	420
Encapsulation	Other organic material	149.785	mg	supplier	Moulding Compound	Amorphous Silica	7631-86-9		91.968	mg	614002	367220
				supplier	Moulding Compound	Quartz	14808-60-7		29.957	mg	200001	119616
				supplier	Moulding Compound	epoxy resin	25068-38-6		17.974	mg	119998	71768
				supplier	Moulding Compound	phenolic resin	29690-82-2		8.987	mg	59999	35884
				supplier	Moulding Compound	Carbon black	1333-86-4		0.899	mg	5999	3588
Finishing	Other inorganic materials	2.104	mg	supplier	connection coating	Tin (Sn)	7440-31-5		2.104	mg	1000000	8400